



Study of Electroless Nickel Plating on Super Duplex Stainless Steel (SDSS)

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ABSTRACT:

The objective of this study is to investigate in detail how electroless nickel plating affects super duplex stainless steel (SDSS), with an emphasis on improving the material's performance in semiconductor silicon wafer processing. The investigation looks into surface modifications and electrochemical changes that occur during nickel plating, such as surface roughness and the differences between the austenite and ferrite phases in SDSS. The intention is to show how these modifications enhance material performance in the semiconductor business.

A number of process parameters, including heat treatment temperature, reducing agent concentration, surfactant type, and particle size, are also examined in the study. The goal is to comprehend how these variables affect mechanical attributes such as protection against corrosion, wear resistance, and hardness. The goal of the study is to offer a thorough understanding of how these components interact during electroless nickel plating through SDSS.

The study's ultimate goal is to improve the SDSS electroless nickel plating process by providing the scientific and industrial communities with useful information. The creation of a tailored and enhanced process is expected to improve the material properties of SDSS and increase its potential uses, especially in the semiconductor sector. The research highlights the critical role of electroless nickel plating in developing materials for high-performance applications, with a focus on semiconductor silicon wafer manufacturing.

KEYWORDS: Electrochemical properties; Super duplex stainless steel; Electroless Ni-plating; Potentiodynamic polarization curve; Passivation layer, Electroless plating; Ni-P; coating; surface; performance; steel.

INTRODUCTION:

Setting out on a thorough investigation into the world of electroless plating, this study combines knowledge from a number of research studies to reveal the many uses and developments in this cutting-edge industry. The journey begins with a careful examination of how plating time affects the characteristics of the nickel electroless coating that is applied to Super Duplex Stainless Steel (SDSS). Inspired by the urgent need for perfect wear resistance and effective nickel-plating capabilities—especially in saw wires, which are crucial for processing silicon wafers—this study takes advantage of SDSS's natural advantages, which include high wear and corrosion resistance due to a high chromium content.

As the story progresses, focus moves to the larger field of electroless nickel-phosphorus (Ni-P) coatings on steel, illuminating their extraordinary qualities and an important part they play in improving the engineering steels' surface performance. This investigation also looks into how well Ni-P coatings adhere to austenitic stainless steel substrates. This section looks at different testing techniques, examines the impact of heat treatment, and emphasizes the role activation processes play in enhancing adhesion.

The trip delves even deeper into the electrochemical characteristics of electroless nickel-plated SDSS, painstakingly dissecting the complex relationship between corrosion resistance and plating. In this instance, the story explains the subtleties of how plating duration affects surface properties and corrosion resistance, revealing knowledge gained from careful testing.

The journey culminates in an investigation into the development of customized membranes for the production of ultra-pure hydrogen. In this situation, electroless plating shows to be essential technology, optimizing workflows, and guaranteeing financial viability. The story emphasizes the never-ending search for novel solutions in a variety of fields and material types, establishing electroless plating as a disruptive force in the ever-evolving field of material science and engineering.

Effects of electroless plating of nickel on stainless steel:

Corrosion Resistance: Increasing corrosion resistance is one of the main advantages. When exposed to corrosive substances or harsh environments, the

nickel layer serves as a protective barrier, preventing the underlying stainless steel from corroding.

Wear Resistance: Electroless nickel plating greatly increases stainless steel's resistance to wear. This is especially crucial in situations where the material will eventually be worn down, abraded, or subjected to friction.

Hardness: The plated nickel layer adds to the surface's increased hardness, which enhances its resilience to wear and tear. This is advantageous in situations where the material might be subjected to abrasive conditions or mechanical stress.

Uniform Coating: Compared to traditional electroplating techniques, electroless plating guarantees a uniform coating on intricate shapes and internal surfaces, which can be difficult to accomplish. This consistent material performance is facilitated by uniformity.

Better solderability and bonding are made possible by the nickel layer, which makes it simpler to connect the plated stainless steel to other components in manufacturing or electronic processes. Additionally, it strengthens the bond with other materials.

Electrical Conductivity: Electrical conductivity may be increased, depending on the plated nickel layer's thickness and makeup. In applications where electrical properties are crucial, this is advantageous.

Aesthetic Appeal: By giving stainless steel a glossy, bright finish, electroless nickel plating can improve its aesthetic appearance. This is frequently preferred in applications such as consumer goods or décor.

Chemical Stability: The stainless steel substrate gains chemical stability from the nickel layer, which increases its resistance to chemical reactions and exposure to the environment.

Dimensional Control: Electroless plating enables accurate control over the plated layer's thickness, guaranteeing that dimensional requirements are satisfied without the need for additional machining.

Materials:

- Super Duplex Stainless Steel (SDSS) UNS S 32750
- Nickel chloride ($\text{NiCl}_2 \cdot 6\text{H}_2\text{O}$)
- Hydrogen chloride (HCl)
- pH adjuster Electrolyte solution
- Saw wires

Configuration for the experiment:

➤ **Getting SDSS Specimens Ready:**

Slice SDSS samples to the appropriate lengths. To get rid of any contaminants, give the specimens a thorough cleaning with an appropriate solvent. The electroless nickel plating solution is prepared as follows: Weigh the necessary quantities of hydrogen chloride (HCl) and nickel chloride ($\text{NiCl}_2 \cdot 6\text{H}_2\text{O}$) in accordance with the guidelines in Table 2. Using a pH adjuster, bring the solution's pH down to 4. To guarantee homogeneity, thoroughly mix the solution.

➤ **Procedure for Electroless Nickel Plating:**

As directed in Table 2, submerge the SDSS specimens in the electroless nickel plating solution. Make sure the mixture is stirred at 350 rpm and at a controlled temperature of 50 °C. Give the samples a specified amount of time (0 to 180 minutes) to be electroplated with nickel.

➤ **Analysis of Microstructure and Roughness:**

After the specimens have been electroless nickel plated, polish them to a #2000 grit. Apply field emission scanning electron microscopy (FE-SEM) to analyse the microstructure. Make use of Atomic Force Microscopy (AFM) to measure surface roughness. Keep notes and information about every specimen.

➤ **Analysis of Electrochemical Properties:**

Assemble the SDSS specimens as the working electrode, a saturated calomel electrode as the reference electrode, and platinum mesh as the counter electrode in a three-electrode cell. In a 3.5 weight percent NaCl electrolyte solution, submerge the cell. Measure the open circuit potential (OCP) for an hour. Perform potentiodynamic polarization at intervals of 0.167 mV, between -0.6 V and 1.2 V. Keep track of data from Electrochemical Impedance Spectroscopy (EIS) between 10^{-1} and 10^4 Hz.

➤ **Calculating the Critical Pitting Temperature (CPT):**

Determine the temperature during potentiodynamic polarization at which the current surpasses $100 \mu\text{A}/\text{cm}^2$ for a duration of more than one minute. Conduct this evaluation in an electrolyte solution containing 5.85 weight percent NaCl (1 mol) at a temperature rate increase of 1 °C per minute and an applied potential of 700 mV.

RESULTS AND DISCUSSION:

➤ **Analysis of Microstructure:**

Several studies have shown that the electroless nickel plating process causes unique microstructural alterations. Longer plating times cause the initial non-uniform coatings to change into more uniform structures.

➤ **Surface attributes:**

As smoother nickel-plated layers form, surface roughness generally shows a trend toward reduction with optimal plating times. After the best plating times, surface features could change, affecting things like corrosion resistance.

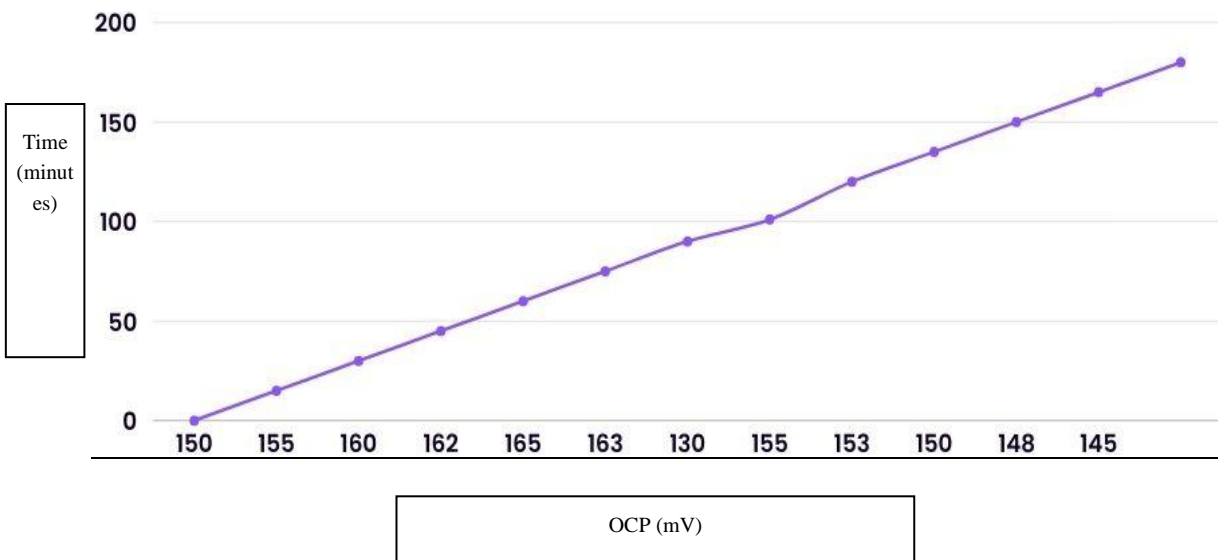
➤ **Properties of Electrochemistry:**

Longer plating times are associated with improved mechanical qualities and improved resistance to corrosion. For uses like saw wire material and stainless steel substrates, the nickel-plated surfaces' electrochemical characteristics are essential.

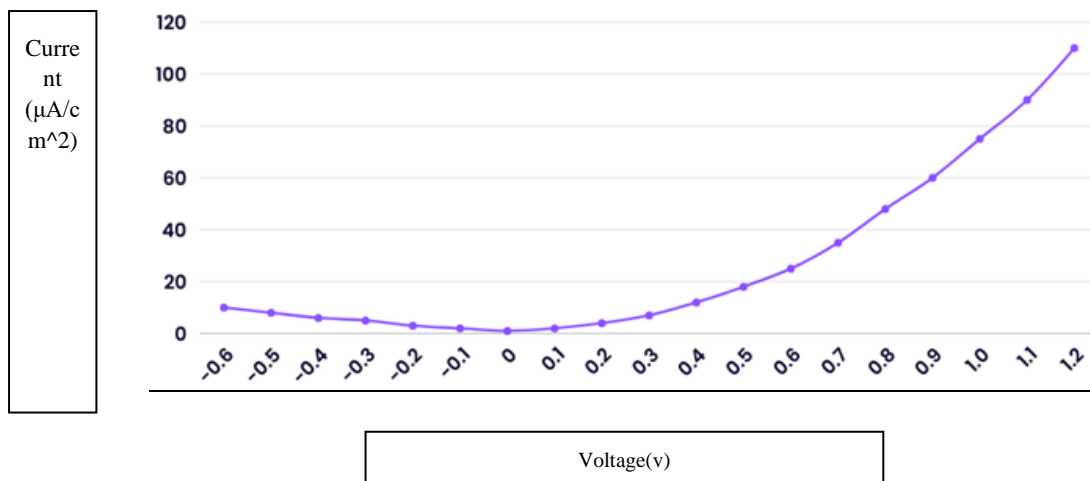
➤ **Selection and Compatibility of Materials:**

Research highlights the significance of material selection, emphasizing the inherent wear and corrosion resistance of super duplex stainless steel (SDSS). Harmony with the application of electroless nickel-phosphorus (Ni-P) coatings on steel demonstrates the compatibility with various substrates, which is a common theme.

Open Circuit Potential (OCP):



Potentiodynamic Polarization Data:



Limitations and Future Directions:

Limitations:

Adhesion Challenges: It can be difficult to get the nickel layer to adhere well to stainless steel, which can result in problems like peeling or separation.

Complex Bath Mixtures: It's important to make the correct bath mix for nickel plating, and doing so can be challenging. Additionally, this procedure might be more expensive than other options.

Expense Elements: Electroless nickel plating involves a number of steps and materials that can be costly.

Environmental Impact: It's critical to find safer alternatives because some of the chemicals used in the process have the potential to harm the environment.

Problems with Uniformity: Electroless plating works well for complex surfaces, but it can be difficult to achieve perfect consistency on large or intricate parts.

Future directions:

Nanolayer Coatings: Investigating ultra-small structures for nickel coatings may enhance corrosion protection, hardness, and wear resistance.

Eco-friendly Methodologies: By employing safer chemicals, research can concentrate on improving the environmental friendliness of the electroless plating process.

Improved Sticking Techniques: Improving surface alterations or layer additions that increase the nickel layer's adhesion to stainless steel may enhance overall performance.

Tailored Solutions: Materials can be improved to perform better for their intended purpose by tailoring electroless nickel plating for particular applications, such as in semiconductors or medical equipment.

Better Bath Mixes: One area for improvement is the discovery of simpler, less expensive, and more efficient bath mixes for electroless plating.

Advanced Methods of Analysis: More reliable coatings can be achieved with improved tools for understanding the plating process, such as real-time monitoring.

Combining with New Tech: Examining the ways in which electroless nickel plating can be integrated with cutting-edge technologies such as smartmaterials, which may result in fascinating applications.

Standards of Quality: Different applications will benefit from the establishment of established guidelines for electroless nickel plating and the maintenance of consistent quality.

Conclusion:

This study aimed to examine the effects of electroless nickel plating on super duplex stainless steel (SDSS) by conducting a number of experiments and analysing the resulting changes in surface characteristics, microstructure, and electrochemical properties. The experimental results shed important light on the possible uses of electroless nickel-plated silicon dielectric semiconductor wafer processing.

Microstructure and Surface Analysis: Following electroless nickel plating, the surface morphology of SDSS underwent a transformation, as demonstrated by the microstructural analysis carried out with Field Emission Scanning Electron Microscopy (FE-SEM) and Atomic Force Microscopy (AFM). Surface roughness decreased as initially irregular coatings developed into more uniform structures. The smoothness of the nickel-plated layer was further highlighted by polishing the specimens up to #2000 grit.

Electrochemical Characteristics: The characteristics of Potentiodynamic polarization, Open Circuit Potential (OCP) measurements, and Electrochemical Impedance Spectroscopy (EIS) were used to analyze the nickel-plated SDSS in detail. OCP readings over time showed that the plated material in a 3.5 weight percent NaCl electrolyte solution behaved steadily. A distinctive corrosion profile was identified by potentiodynamic polarization curves, along with the determination of the Critical Pitting Temperature (CPT). The significance of regulated plating times was highlighted by the observation of a decline in corrosion resistance beyond ideal plating durations.

Significance and Uses: This study's findings shed light on how electroless nickel plating can improve SDSS performance, making it a potentially useful material for use in semiconductor manufacturing. Saw wire requirements are well-met by the enhanced wear resistance, reduced surface roughness, and optimized electrochemical properties utilized when processing silicon wafers.

Future Directions: Although this study offers insightful information, more research could focus on improving plating conditions, looking into different electrolyte solutions, and examining the plated material's long-term stability. Furthermore, more research should be done on the useful uses of electroless nickel-plated SDSS in actual semiconductor manufacturing settings.

To sum up, the study's experimental findings highlight the potential of electroless nickel-plated silicon dioxide silicon wafer (SDSS) as a resilient and corrosion-resistant material. This could lead to further advancements in material science and engineering.

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